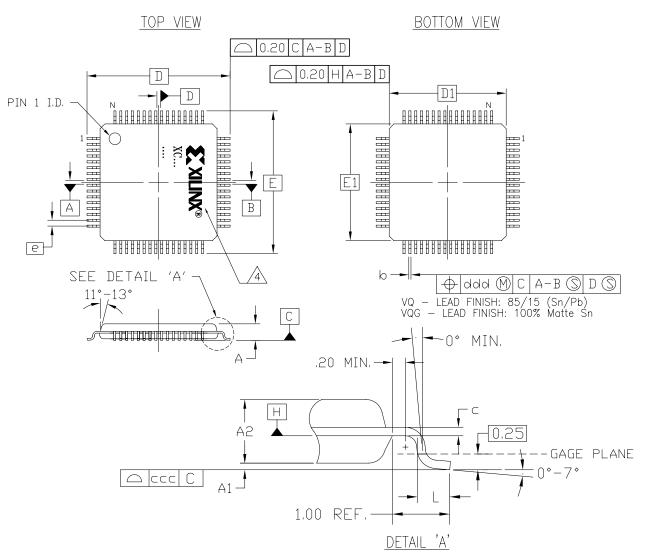
VQFP (VQ100/VQG100) Package



VQ/VQG44						
S Y M	MILLIMETERS					
SYMBOL	MIN.	N□M.	MAX.			
Α	X	~~	1.20			
A_1	0.05	~~	0.15			
Αz	0.95	1.00	1.05			
D/E	12.00 BSC					
D_1/E_1	10.00 BSC					
b	0.30	0.37	0.45			
\subset	0.09	~~	0.20			
е	0.80 BSC.					
L	0.45	0.60	0.75			
CCC	1/2	~~	0.10			
ddd	¥	×	0,20			
N	44					
REF.	JEDEC MS-026-ACB					

VQ/VQG64				∨Q/∨QG100			
MILLIMETERS				MILLIMETERS			
MIN.	N□M.	MAX.		MIN.	N□M.	MAX.	
×	~	1.20		X	×	1.20	
0.05	0.10	0.15		0.05	0.10	0.15	
0.95	1.00	1.05		0.95	1.00	1.05	
12.00 BSC.				16.00 BSC.			
10.00 BSC.				14.00 BSC.			
0.17	0.22	0.27		0.17	0.22	0.27	
0.09	~~	0.20		0.09	~~	0.20	
0.50 BSC.				0.50 BSC.			
0.45	0.60	0.75		0.45	0.60	0.75	
×	~	0.08		×	~~	0.08	
X	~~	0.08		X	~~	0.08	
64				100			
JEDEC MS-026-ACD				JEDEC MS-026-AED			

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- 2. PACKAGE BODY DIMENSIONS "D1/E1" DO NOT INCLUDE MOLD PROTRUSIONS. ALLOWABLE MOLD PROTRUSIONS SHALL NOT EXCEED 0.25mm PER SIDE.
- 3. THE TOP OF THE PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15mm.
- MARK ORIENTATION WITH RESPECT TO PIN-1 I.D. IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE THE SMALLEST CIRCLE AS PIN-1 I.D.

44, 64, and 100-PIN PLASTIC VERY THIN QFP (VQ44/VQG44, VQ64/VQG64, and VQ100/VQG100)

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision	
6/18/04	1.2	Xilinx Initial Release	
2/26/07	1.2.1	Minor update to clarify Note #2.	